

# ROG254A

MIL-STD-810G 19" RACKMOUNT FANLESS  
COMPUTER WITH INTEL® XEON® D-2141I/  
D-2166NT / D-2183IT PROCESSOR



- MIL-STD 810G COMPLIANCE
- INTEL® XEON® D-2141I/D-2166NT/D-2183IT PROCESSOR
- UP TO 128GB REGISTERED ECC RDIMM DDR4-2400MHZ
- 1 X VGA , 6 X USB PORTS
- 2 X GIGABIT ETHERNET, 1 X IPMI
- 1 X PCIe 3.0 X16 EXPANSION SLOT
- EXTENDED TEMPERATURE -10 TO 60 °C



Extended  
Temperature  
+60°C  
-10°C

**SPECIFICATIONS**

<b>SPECIFICATIONS</b>	
High Performance Processor	Intel® Xeon® Processor D-2141I /D-2166NT / D-2183IT (8 / 12 / 16 Core,16 / 24 / 32 Thread Support) Build-in Turbo Boost Technology 2.0, VPro and Hyper-Threading support
Memory	Up to 128GB ECC RDIMM DDR4-2400MHz
Chipset	System on Chip
Expansion Slot	1 x PCI-E 3.0 x16
<b>DISPLAY</b>	
VGA	Resolution up to 1920x1200@60Hz
<b>STORAGE</b>	
Storage Device	2 x 2.5" Solid State Disk (SSD) 64 / 128 / 256 / 512GB /1TB / 2TB Innodisk 3MG2-P Series MLC SATA III 6Gb/s Flash SSD, Rated for 520 MB/sec Sequential Read ; 350 MB/sec Write Max.
<b>ETHERNET</b>	
Ethernet	1 x Intel I350-AM2 Gigabit Ethernet LAN Interfaces (10/100/1000Mbps)
<b>REAR I/O</b>	
Ethernet	2 x RJ45 Gigabit Ethernet LAN Interfaces 1 x IPMI LAN Interface
VGA Port	1 x DB15 connector
USB Port	2 x USB3.0 standard-A connectors 2 x USB2.0 standard-A connectors
AC-IN	1 x IEC C14 Plug
<b>FRONT I/O</b>	
Button	1 x Power Button w/Indicator LED
Indicator LED	1 x HDD LED
USB Port	2 x USB2.0 standard-A connectors
SSD Tray	2 x 2.5 SSD Easy Swap Tray
<b>POWER REQUIREMENT</b>	
Power Input	90V to 264V AC-in, 200W max

**APPLICATIONS, OPERATING SYSTEM**

Applications	Commercial and Military Platforms Requiring Compliance to MIL-STD-810G Embedded Computing, Process Control, Intelligent Automation and manufacturing applications where Harsh Temperature, Shock, Vibration, Altitude, Dust and EMI Conditions. Used in all aspects of the military.
Operating System	Windows 10 64Bit, Windows Server 2008 R2, Windows Server 2012 R2 Ubuntu14.04, Fedora 20/23, RedHat Linux EL 7.1/7.2, Vmware ESXi 6.0, ESXi 6.5

**PHYSICAL**

Dimension (W x D x H)	430 x 380 x 44.6mm
Weight	TBD
Chassis	SECC
Finish	Anodic aluminum oxide (Black)
Cooling	Natural Passive Convection/Conduction. No Moving Parts
Ingress Protection	Dust Proof (Similar to IP50)

**ENVIRONMENTAL**

MIL-STD-810G Test	Method 507.5, Procedure II (Temperature & Humidity) Method 516.6 Shock-Procedure V Non-Operating (Mechanical Shock) Method 516.6 Shock-Procedure I Operating (Mechanical Shock) Method 514.6 Vibration Category 24/Non-Operating (Category 20 & 24, Vibration) Method 514.6 Vibration Category 20/Operating (Category 20 & 24, Vibration) Method 501.5, Procedure I (Storage/High Temperature) Method 501.5, Procedure II (Operation/High Temperature) Method 502.5, Procedure I (Storage/Low Temperature) Method 502.5, Procedure II (Operation/Low Temperature) Method 503.5, Procedure I (Temperature shock)
Operating Temperature	-10 to 60°C (ambient with 0.7m/s airflow)
Storage Temperature	-40 to 85°C
EMC	CE and FCC compliance

**ORDERING INFORMATION**

**ROC255A**

**MIL-STD-810G 19" RACKMOUNT FANLESS COMPUTER WITH INTEL® XEON® D-2141I PROCESSOR , 1 X VGA, 1 X IPMI , 2 X GIGABIT ETHERNET, 6 X USB PORTS**

**ROC255A - 1**

**MIL-STD-810G 19" RACKMOUNT FANLESS COMPUTER WITH INTEL® XEON® D-2166NT PROCESSOR , 1 X VGA, 1 X IPMI , 2 X GIGABIT ETHERNET, 6 X USB PORTS**

DIMENSION

**ROC255A - 2**

MIL-STD-810G 19" RACKMOUNT FANLESS COMPUTER WITH INTEL® XEON® D-2183IT PROCESSOR , 1 x VGA, 1 x IPMI , 2 x GIGABIT ETHERNET, 6 x USB PORTS

